



Patent

UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: VANDENTOP et al.

Application No.: 10/667,694

Filing Date: 9/22/2003

For: INTEGRATED CIRCUIT  
DIE/PACKAGE INTERCONNECT

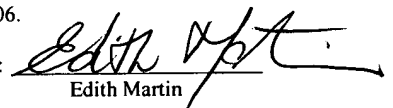
) Confirmation No.: 9242  
)  
) Group Art Unit: 2841  
)  
) Examiner: Tuan T. Dinh  
)  
) **AMENDMENT and RESPONSE to**  
) **September 20, 2006 Non-Final Office Action**  
)  
) Attorney Docket No.: P16922  
)  
) **PTO Customer Number 28062**  
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)

**CERTIFICATE OF MAILING UNDER 37 CFR 1.8**

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22133-1450, on November 20, 2006.

Dated: November 20, 2006

By:

  
Edith Martin

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22133-1450

Sir:

In response to the Non-Final Office Action mailed September 20, 2006, please amend the above-identified application as follows:

**Amendments to the claims** are reflected in the listing of claims which begins on page 2 of this paper.

**Remarks** begin on page 8 of this paper.